

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHUNG-YING YANG</td> <td>09/28/2011</td> </tr> <tr> <td>HSIEN-WEI CHEN</td> <td>09/28/2011</td> </tr> <tr> <td>TSUNG-YUAN YU</td> <td>09/28/2011</td> </tr> <tr> <td>SHIH-WEI LIANG</td> <td>09/30/2011</td> </tr> </tbody> </table>		Name	Execution Date	CHUNG-YING YANG	09/28/2011	HSIEN-WEI CHEN	09/28/2011	TSUNG-YUAN YU	09/28/2011	SHIH-WEI LIANG	09/30/2011
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SHIH-WEI LIANG	09/30/2011										
RECEIVING PARTY DATA											
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.										
Street Address:	NO. 8, LI-HSIN RD. VI										
Internal Address:	HSINCHU SCIENCE PARK										
City:	HSINCHU										
State/Country:	TAIWAN										
Postal Code:	300										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14100104</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14100104						
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Application Number:	14100104										
CORRESPONDENCE DATA											
Fax Number:											
Phone:	7036841111										
Email:	tsmc@ipfirm.com										
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
Correspondent Name:	LOWE HAUPTMAN & HAM, LLP (TSMC)										
Address Line 1:	2318 MILL ROAD										
Address Line 2:	SUITE 1400										
Address Line 4:	ALEXANDRIA, VIRGINIA 22314										
ATTORNEY DOCKET NUMBER:	T5057-Y495A										
NAME OF SUBMITTER:	RANDY A. NORANBROCK										

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Signature:	/Randy A. Noranbrock/
Date:	12/09/2013
Total Attachments: 1 source=efiledassgn#page1.tif	

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Chung-Ying YANG
- 2) Hsien-Wei CHEN
- 3) Tsung-Yuan YU
- 4) Shih-Wei LIANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

WAFER LEVLE CHIP SCALE PACAKAGE AND METHOD OF MANUFACTURING THE SAME

- (a) for which an application for United States Letters Patent was filed on 2011-10-05, and identified by United States Patent Application No. 13/253,845; or
- (b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chung-ying Yang
Name: Chung-Ying YANG

2011. 9. 28
Date:

2) Hsien-Wei Chen
Name: Hsien-Wei CHEN

2011. 09. 28
Date:

3) Tsung-Yuan Yu
Name: Tsung-Yuan YU

2011. 09. 28
Date:

4) Shih-Wei Liang
Name: Shih-Wei LIANG

2011. 9. 30
Date: